

Amendments to the Claims:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

Listing of Claims:

1. (Original) A connection board comprising an insulating resin composition layer formed of one layer or two or more layers and a connection conductor which is formed so as to pass through the insulating resin composition layer in its thickness direction at least at a position where a conductor circuit is connected.

2. (Original) The connection board according to claim 1 further comprising a conductor circuit which is electrically connected to the connection conductor for at least one surface of the connection board.

3. (Original) The connection board according to claim 2, wherein the conductor circuit is a metallic layer.

4. (Original) The connection board according to any one of claims 1 to 3, wherein an exposed portion of the connection conductor is covered with metal.

5. (Previously Presented) The connection board according to any one of claims 1 to 3 wherein one of the insulating resin compositions placed at front and rear outermost layers of the connection board is or both of them are mainly made of thermoplastic resin.

6.-12. (Cancelled)

13. (Previously Presented) A multi-layer wiring board in which connection conductors or a connection conductor and conductor circuit of at least two connection boards obtained by being arbitrarily selected from connection boards according to any one of claims 1 to 3 are made into an alloy by solid phase metallic diffusion or melt bonding and conductive connected with each other, and the connection boards are mechanically connected with each other by an insulating resin composition.

14. (Original) The multi-layer wiring board according to claim 13, wherein an insulating resin composition layer of the connection board is a liquid crystal polymer.

15.-18. (Cancelled)

19. (Previously Presented) A substrate for semiconductor package having the multi-layer wiring board according to claim 13.

20. (Original) The substrate for semiconductor package according to claim 19 comprising a cavity at a position where a semiconductor chip is mounted.

21. and 22. (Cancelled)

23. (Previously Presented) A semiconductor package manufactured by using the substrate for semiconductor package according to claim 19.

24.-26. (Cancelled)

27. (Previously Presented) A multi-layer wiring board in which connection conductors or a connection conductor and conductor circuit of at least two connection boards obtained by being arbitrarily selected from connection boards according to any one of claim 4 are made into an alloy by solid phase metallic diffusion or melt bonding and conductive connected with each other, and the connection boards are mechanically connected with each other by an insulating resin composition.

28. (Previously Presented) A multi-layer wiring board in which connection conductors or a connection conductor and conductor circuit of at least two connection boards obtained by being arbitrarily selected from connection boards according to any one of claim 5 are made into an alloy by solid phase metallic diffusion or melt bonding and conductive connected with each other, and the connection boards are mechanically connected with each other by an insulating resin composition.

29.-32. (Cancelled)

33. (Previously Presented) A substrate for semiconductor package having the multi-layer wiring board according to claim 14.

34. (Previously Presented) The multi-layer wiring board obtained by the manufacturing method according to claim 15.

35. (Previously Presented) The multi-layer wiring board obtained by the manufacturing method according to claim 16.

36. (Cancelled)

37. (Previously Presented) A semiconductor package manufactured by using the substrate for semiconductor package according to claim 20.

38. and 39. (Cancelled)